

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) An electronic device comprising:
 - a first housing comprising a first face;
 - a second housing comprising a second face;
 - the second face indented from the first face;
 - a plurality of electronic components housed in the first housing;
 - one or more power supplies housed in the second housing; and
 - the electronic components operable to be powered by a cord to the one or more of the plurality of power supplies, the cord running from the indented second face to the first face.
2. (Original) The device of claim 1 wherein the second face is higher than the first face.
3. (Original) The device of claim 1 wherein the second face is lower than the first face.
4. (Original) The device of claim 1 the one or more power supplies is a plurality of power supplies.
5. (Previously Presented) The device of claim 4 wherein at least two of the power supplies are disposed in separate sub-housings of the second housing, separated by a structure disposed within the second housing.

6. (Previously Presented) The device of claim 5 further comprising a cover, the cover operable to project an outline upon the indentation that corresponds to the dimension of the first face.
7. (Previously Presented) The device of claim 6 wherein the cover comprises structures that correspond to the structures disposed within the second housing.
8. (Previously Presented) The device of claim 1 further comprising a cover, the cover operable to project an outline upon the indentation that corresponds to the dimension of the first face.
9. (Previously Presented) The device of claim 1 wherein the second housing is operable to be coupled to the first housing.
10. (Previously Presented) The device of claim 1 wherein the first face is parallel to the second face.
11. (Previously Presented) The device of claim 1 wherein the first face is not parallel to the second face.
12. (Currently Amended) An enclosure for an electronic system comprising:
 - a first chassis, operable to enclose a plurality of electronic components, comprising:
 - a first face;
 - a second face opposite the first face;
 - a third face, wherein the plane of the third face is perpendicular to the planes of the first face and the second face;

~~electrical connections, for transferring electrical energy to any enclosed electronic~~

~~components, disposed through the first face;~~

a second ~~chassis~~, chassis operable to enclose one or more power supplies, the second chassis

having a fourth face indented from the first face; and

one or more cords running from the first fact to the fourth face, the one or more cords

operable to supply power from the one or more power supplies to at least one of the

plurality of electronic components.

~~wherein a portion of the fourth face is disposed in a plane that intersects the third face.~~

13. (Original) The enclosure of claim 12 wherein the second chassis is higher than the first chassis.
14. (Original) The enclosure of claim 12 wherein the second chassis is lower than the first chassis.
15. (Original) The enclosure of claim 12 the second chassis is operable to enclose a plurality of power supplies.
16. (Previously Presented) The enclosure of claim 15 wherein at least two of power supplies are operable to be disposed in separate sub-housing of the second chassis, separated by a structure disposed within the second chassis.

17. (Previously Presented) The enclosure of claim 16 further comprising a cover, the cover operable to project an outline upon the second chassis that corresponds to the dimension of the first face.
18. (Previously Presented) The enclosure of claim 17 wherein the cover comprises structures that corresponds to the structures disposed within the second chassis.
19. (Previously Presented) The enclosure of claim 12 further comprising a cover, the cover operable to project an outline upon the indentation that corresponds to the dimension of the first face.
20. (Original) The enclosure of claim 12 wherein the second chassis is operable to be selectively coupled to and uncoupled from the first chassis.
21. (Previously Presented) The enclosure of claim 12 wherein the first face is parallel to the second face.
22. (Previously Presented) The enclosure of claim 12 wherein the first face is not parallel to the second face.
23. (Original) The enclosure of claim 12 further comprising a plurality of first chasses.
24. (Original) The enclosure of claim 12 further comprising a plurality of second chasses.

25. (Currently Amended) An enclosure for an electronic system comprising:
- a first chassis operable to enclose a plurality of electronic components, the first chassis comprising a first face and a second face opposite the first face;
 - ~~electrical connections, for transferring electrical energy to any enclosed electronic components, disposed through the first face;~~
 - a second chassis operable to enclose one or more power supplies, comprising a third face;
 - and
 - one or more cords running from the first fact to the third face, the one or more cords operable to supply power from the one or more power supplies to at least one of the plurality of electronic components; and
- wherein the third face and the first face define an indentation, and the second chassis is indented from the first chassis.
26. (Original) The enclosure of claim 25 wherein the second chassis is higher than the first chassis.
27. (Original) The enclosure of claim 25 wherein the second chassis is lower than the first chassis.
28. (Original) The enclosure of claim 25 the second chassis is operable to enclose a plurality of power supplies.

29. (Previously Presented) The enclosure of claim 28 wherein at least two of power supplies are operable to be disposed in separate sub-housing of the second chassis, separated by a structure disposed within the second chassis.
30. (Previously Presented) The enclosure of claim 29 further comprising a cover, the cover operable to project an outline upon the second chassis that corresponds to the dimension of the first face.
31. (Previously Presented) The enclosure of claim 30 wherein the cover comprises structures that corresponds to the structures disposed within the second chassis.
32. (Previously Presented) The enclosure of claim 25 further comprising a cover, the cover operable to project an outline upon the indentation that corresponds to the dimension of the first face.
33. (Original) The enclosure of claim 25 wherein the second chassis is operable to be selectively coupled to and uncoupled from the first chassis.
34. (Previously Presented) The enclosure of claim 25 wherein the first face is parallel to the third face.
35. (Previously Presented) The enclosure of claim 25 wherein the first face is not parallel to the third face.

36. (Original) The enclosure of claim 25 further comprising a plurality of first chasses.
37. (Original) The enclosure of claim 25 further comprising a plurality of second chasses.
38. (Original) An enclosure for an electronic system comprising:
- means for enclosing a plurality of electronic components, defined by a first face and a second face opposite the first face;
 - means for making electrical connections disposed through the first face;
 - means for enclosing one or more power supplies, defined at least in part by a third face; and
 - wherein the third face and the first face define an indentation.
39. (New) The electronic device of Claim 1 wherein
- the first face comprises a back face of the first housing; and
 - the second face comprises a back face of the second housing.
40. (New) The enclosure of Claim 12 wherein
- the first face comprises a back face of the first chassis; and
 - the fourth face comprises a back face of the second chassis.
41. (New) The enclosure of Claim 25 wherein
- the first face comprises a back face of the first chassis; and
 - the third face comprises a back face of the second chassis.